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The IEEE WiMob conference is an international forum for the exchange of experience and knowledge among researchers and developers concerned with wireless and mobile technology. For fourteen years, the International IEEE WiMob conference has provided unique opportunities for researchers to interact, share new results, show live demonstrations, and discuss emerging directions in - Wireless Communication, - Wireless Networking, Mobility and Nomadicity, - Ubiquitous Computing, Services and Applications, - Green and sustainable communications and network computing and - Security on Wireless and mobile Networks.

IEEE WiMob 2023 will take place in Montreal, Canada, during 21-23 June, 2023.

IEEE WiMob 2023 is soliciting high quality technical papers addressing research challenges in the areas of wireless communications, wireless networking, mobility, nomadicity, ubiquitous computing, services and applications. Papers should present original work validated via analysis, simulation or experimentation. Practical experiences and Testbed trials also are welcome.

IEEE WiMob 2023 will host FIVE parallel symposia, including but not limited to the following topics:

- Wireless Communications (WC)
- Wireless Networking, Mobility and Nomadicity (WNMN)
- Ubiquitous Computing, Services and Applications (UCSA)
- Green and Sustainable Communications and Network Computing (GSCN)
- Security on Wireless and Mobile Networks (SWMN)

IMPORTANT DATES

Papers Submission: ~~March 1, 2023~~ extended to March 28, 2023
Notification of Acceptance: April 28, 2023
Camera Ready & Author Registration: May 19, 2023

INSTRUCTIONS FOR PAPER SUBMISSION

Authors are required to submit fully formatted, original papers (PDF), with graphs, images, and other special areas arranged as intended for the final publication.

Papers should be written in English conforming to the IEEE standard conference format (8.5" x 11" - US letter, Two-Column). The initial submission for review will be limited to 8 pages. The final manuscript for publication will be limited to 8 IEEE pages. Additional charges may apply for additional pages.

Conference content will be submitted for inclusion into IEEE Xplore as well as other Abstracting and Indexing (A&I) databases.

Each accepted paper must be presented at the conference by one of the co-authors or a third party.

Only timely submissions through EDAS [here](#) will be accepted.

For more details please visit the WiMob 2023 official website (www.wimob.org/wimob2023).

ACCEPTED PAPERS

All accepted papers will be published in the conference proceedings and will be accessible via the IEEE Xplore Digital Library.

